



Q1 2025

Market Insights



Rebound
Electronics

Semiconductor Industry Market Outlook



Global Semiconductor Manufacturing: Insights from Q1 & What's Next

As we look ahead to the second quarter of 2025, the global semiconductor manufacturing industry is poised for continued growth, driven by robust demand in artificial intelligence (AI) applications, high-bandwidth memory (HBM) chips, and strategic investments by key industry players.

Market Growth Projections:

Revenue Growth

The global semiconductor market is **forecasted to grow by 15% in 2025**, with the memory segment expected to surge by over 24%, according to IDC report. This growth is primarily attributed to the increasing adoption of high-end products such as HBM3 and HBM3e, essential for AI accelerators.

Regional Performance:

The Americas and Asia-Pacific regions are anticipated to lead the industry's expansion, with projected growth rates of **38.9%** and **17.5%**, respectively, based on the Report of WSTS.

Key Industry Developments:

Micron Technology's Upbeat Forecast: Micron projects higher-than-expected revenue for the upcoming quarter, driven by robust demand for its HBM chips, which are crucial for AI systems. The company has reported that its HBM chip supply for 2025 is already sold out, reflecting strong market demand.

Nvidia's Significant Investment: **Nvidia plans to invest around \$500 billion** over the next four years to enhance its electronics supply chain, with a substantial portion earmarked for U.S. manufacturing. This strategic move aligns with efforts to mitigate geopolitical risks and strengthen domestic production capabilities.

Samsung's Pursuit of M&A Opportunities: Facing challenges in the AI sector, Samsung Electronics intends to engage in significant mergers and acquisitions to bolster growth. The company acknowledges the need to regain competitiveness in the HBM market and is exploring strategic initiatives to address this gap.

Passive Components Market:

Demand for passive components has surged by 55% compared to 2024, driven by increased industry requirements. Manufacturers such as Vishay, AVX, TDK, Murata, and Rohm have experienced significant order growth, particularly for Rohm's product range. Supply chain constraints may lead to longer lead times for certain passive components.

Emerging Trends:

AI Integration in Consumer Devices: The integration of AI capabilities into personal computers and smartphones is expected to drive semiconductor demand. As AI becomes more prevalent in consumer electronics, the need for advanced semiconductors to support these functionalities will increase.

Supply Chain Resilience: In response to geopolitical tensions and trade policies, companies are diversifying their supply chains to enhance resilience. This shift includes increasing manufacturing capacities in regions like the United States to mitigate risks associated with global dependencies.

Outlook for Q2 2025:

The semiconductor industry is expected to maintain its growth trajectory in the second quarter of 2025, propelled by sustained demand for AI applications and strategic investments by leading companies. However, challenges such as talent shortages and geopolitical uncertainties may influence the pace of expansion, as per Deloitte, US reports. As we analyse the global semiconductor manufacturing industry in Q1 2025 and look ahead, several challenges and considerations emerge that are pivotal to the industry's trajectory:

1. Inventory Management:

The semiconductor industry is transitioning from a period of excess inventory, which had previously constrained the global market. This surplus is now largely resolved, setting the stage for a typical growth cycle in the coming year. However, companies must remain vigilant, as 2025 may still present uncertainties that could impact inventory levels and demand forecasting.

2. Supply Chain Disruptions:

The industry continues to face challenges such as supply chain strains and underinvestment in mature nodes. Geopolitical tensions and infrastructure costs further complicate the landscape, necessitating more resilient strategies to mitigate risks and navigate uncertainties.

3. Technological Advancements and Long-Term Growth:

The semiconductor sector is poised for significant growth, driven by advancements in artificial intelligence (AI), electric vehicles (EVs), and high-performance computing. Based on PCIM report, Revenue is expected to reach \$717 billion in 2025, reflecting the industry's robust expansion.

4. Investment in Research and Development (R&D):

Collaborations between industry leaders are crucial for driving innovation. For instance, ASML and imec have entered a five-year strategic partnership focusing on semiconductor research and sustainable innovation. Such alliances are essential for maintaining competitiveness and addressing emerging technological challenges.

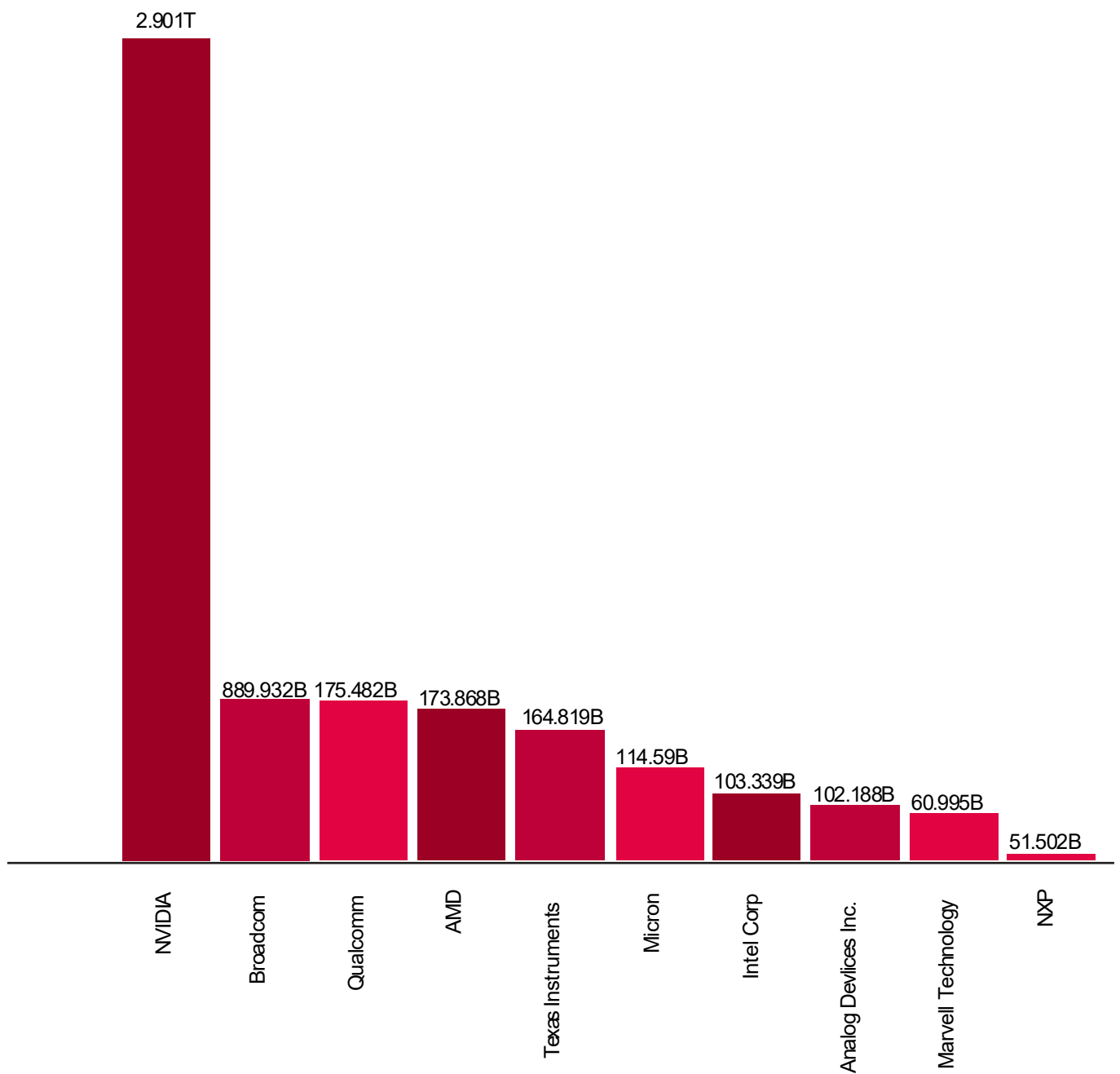
5. Sustainable Initiatives:

Environmental considerations are becoming increasingly important in semiconductor manufacturing. A recent study suggests that Europe should focus on sustainable chip production, especially as emissions from manufacturing cutting-edge chips rise. Emphasising lower-emission semiconductor production could provide a competitive advantage while addressing environmental concerns.

In summary, the semiconductor industry in 2025 is navigating a complex landscape marked by supply chain challenges, technological advancements, and a heightened focus on sustainability. Strategic investments in R&D and sustainable practices will be critical for companies aiming to thrive in this evolving environment.

Semiconductor Industry Stocks

Largest Companies in the Industry (Q1 2025)



Key U.S. Semiconductor Tariffs & Policies

Trade tariffs in the U.S. semiconductor industry refer to government-imposed duties on imported semiconductor components, chips, and related materials. These tariffs are often used as a tool to protect domestic semiconductor manufacturers, counter foreign subsidies, and reduce dependency on specific countries like China and Taiwan. However, they also have significant consequences for global supply chains, production costs, and technological innovation.

Key U.S. Semiconductor Tariffs & Policies

1. Tariffs on Chinese Semiconductors

Since the Trump administration, the U.S. has imposed tariffs on Chinese-made chips and semiconductor equipment as part of the trade war.

In 2018, the U.S. imposed a 25% tariff on Chinese semiconductors under Section 301 of the Trade Act. The Biden administration has maintained these tariffs and initiated new investigations into Chinese legacy chips, which could lead to further restrictions.

2. Potential Tariffs on Taiwan & South Korea

The U.S. is considering imposing up to 100% tariffs on Taiwan Semiconductor Manufacturing Company (TSMC) and other Taiwanese chipmakers.

South Korea's semiconductor industry (Samsung & SK Hynix) could also face increased tariffs as the U.S. pushes for domestic chip production.

3. Tariffs on Semiconductor Equipment

The U.S. has imposed restrictions on the export of advanced chip-making tools (e.g., lithography machines) to China.

Companies like ASML, Nvidia, and AMD have been restricted from selling advanced semiconductor technology to Chinese firms.

Implications of Semiconductor Tariffs

- Increased Manufacturing Costs
- Shift Toward Domestic Manufacturing
- China's Response & Supply Chain Disruptions

Industry Responses and Investments

Nvidia's Expansion: In response to these tariffs, Nvidia plans to significantly expand its U.S. supply chain, potentially investing several hundred billion dollars in domestic chip and electronics manufacturing over the next four years.

CHIPS Act Developments: The CHIPS Act has been instrumental in attracting substantial investments in U.S. semiconductor manufacturing. Notably, Taiwan Semiconductor Manufacturing Company (TSMC) committed \$100 billion to its Arizona facilities, enhancing U.S. national security by bolstering domestic chip production.

Market Updates by Company – March 2025



Analog Devices Inc. (ADI)

ADI has announced the termination of its franchise agreement with WT Micro, with orders accepted until the end of April and deliveries ceasing by June 2025. The official agency relationship will end on July 26, 2025, as part of ADI's global sales strategy adjustments. Customers are advised to finalise their ADI product orders before mid-April to avoid supply disruptions.

Nvidia

Nvidia has reportedly shifted some of its orders from Monolithic Power Systems (MPS) to Infineon, impacting SLB Series production and extending lead times. Last year, similar supply chain disruptions led to a shortage of MP5991GLU-Z due to Nvidia's demand. While there is no official confirmation, multiple industry sources in China have reported the change.

NXP Semiconductors

NXP's pricing remains relatively stable, though certain product numbers have experienced price increases. Automotive chip demand has weakened, leading to inventory pressures, particularly for general automotive components. Wenyue has overtaken Arrow to become the world's largest distributor, generating \$29.3 billion in annual revenue.

Texas Instruments (TI)

TI has seen a slight price increase with a reduction in loss-making shipments, stabilising profitability. Most general materials are operating at low margins with a rapid turnover strategy to optimise inventory and cash flow. Additionally, reports indicate internal restructuring efforts, integrating new employees into TI's systems.

Infineon

Infineon's BTT, BTS, BSC, and IR-series are facing severe shortages, significantly extending lead times. Some end customers are experiencing delays of up to three months compared to their requested delivery schedules. The BTT-series, which operates on 24V systems for engineering vehicles, is the most affected.

STMicroelectronics (ST)

ST's industrial revenue dropped by 49%, while automotive revenue fell by 14% in 2024. The company plans to lay off approximately 2,000–3,000 employees, amounting to a 6% workforce reduction. Temporary plant closures are expected this quarter as ST adjusts its operations to market conditions

Panasonic

Factory Fire Incident

A fire at Panasonic's Chitose facility in Japan on March 9 has halted production of key electronic components, including varistors and thermistors. Recovery efforts are ongoing, with estimated production resumption expected within 3–6 months. Customers are advised to consider alternative suppliers during this period.

Data Falsification Issue

Panasonic has disclosed long-term data falsification related to relay durability testing, impacting product reliability claims. While no official public statement has been made, select clients have been informed, and warranty responses are being handled by distributors. Increased demand for Littelfuse varistors, a replacement for Panasonic's affected components, has extended lead times.

WECO Hanau (Germany)

WECO Hanau filed for insolvency in November 2024, with court approval granted in December. Due to financial challenges, the facility will cease operations by June 2025, with production shifting to WECO Tunisia. Customers are encouraged to prioritize orders and update payment terms to avoid disruptions.

Toshiba, Avago & Broadcom

Toshiba's TBD series prices will rise by 80%, impacting procurement costs for affected customers. Avago's pricing remains stable for now, while Broadcom products face supply shortages. A new batch of Avago products is available with competitive pricing for customers looking for alternative sourcing options.

Latest Updates from Industry Leaders

AMD

- AMD has captured 45% of Japan's gaming GPU market, attributing its success to strong Radeon sales while acknowledging its unfamiliarity with such high demand.
 - AMD's Radeon 9070 and 9070 XT GPUs are already being scalped above MSRP just a week after launch.
 - AMD is launching its Ryzen 9 9950X3D and 9900X3D gaming processors on March 12, promising top-tier performance for both gaming and content creation.
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Analog Devices

- Analog Devices (ADI) reported strong FY2024 growth, securing \$105M under the CHIPS Act, and continues driving AI innovation with SambaNova Suite integration.
 - Mouser Electronics now stocks over 70,000 Analog Devices (ADI) products, including advanced sensors, power regulators, and data acquisition systems for robotics, automation, and precision applications.
 - Analog Devices has expanded CodeFusion Studio with System Planner for streamlined resource allocation and Data Provenance for secure, traceable data, accelerating intelligent edge development.
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Broadcom

- Broadcom patched three actively exploited VMware zero-days (CVE-2025-22224, CVE-2025-22225, CVE-2025-22226) that allow attackers with admin access to escape virtual machine sandboxes.
 - Broadcom's 14% stock surge followed a strong Q2 forecast, highlighting growing AI chip demand and new hyperscale customers investing in custom processors.
 - Nvidia and Broadcom are testing Intel's 18A manufacturing process, signaling potential confidence in Intel's struggling foundry business despite ongoing delays and uncertainty.
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Diodes Inc.

- Diodes Inc. stock hit a 52-week low at \$46.56 amid market challenges, following weaker-than-expected Q4 earnings, but analysts see potential upside with a focus on automotive and AI market expansion.
- Diodes Incorporated exceeded Q4 2024 revenue expectations with \$339.3 million, achieving 5% year-over-year growth despite global demand challenges, while maintaining strong momentum in Asia and a strategic focus on automotive, industrial, and AI markets.
- Diodes Incorporated continues to expand its portfolio with advanced automotive, high-speed connectivity, and power management solutions, including new USB Type-C®, PCIe 6.0, and high-voltage power products.

Infinion

- Infineon plans to double its workforce in India by 2030, focusing on expanding its R&D operations and supporting local startups and educational collaborations to bolster India's semiconductor industry.
 - Infineon is expanding its AURIX portfolio with new automotive RISC-V MCUs, aiming to enhance efficiency, scalability, and software portability in software-defined vehicles.
 - SkyWater is acquiring Infineon's Austin fab to expand U.S. foundry capacity for critical industrial, automotive, and defense chips, ensuring long-term supply and strengthening domestic semiconductor manufacturing.
 - Infineon unveils a groundbreaking 12kW battery backup unit (BBU) for AI data centers, leveraging Si, SiC, and GaN to enhance energy efficiency and meet surging AI-driven power demands.
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Intel

- Intel has delayed its \$28 billion Ohio semiconductor factory to 2030-2031, citing financial struggles and market alignment needs. Despite setbacks, the company has already invested \$3.7 billion locally and remains committed to the project.
 - Intel shares surged 15% after appointing Lip-Bu Tan as CEO. Tan, a former board member, is tasked with reviving the struggling chipmaker after years of losses and missing the AI boom. Analysts believe his industry connections and foundry strategy could help turn the company around.
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Kyocera

- Kyocera will debut cutting-edge innovations in AI, autonomous driving, and wireless tech, including aerial displays and GaN Kyocera Document Solutions has been recognised for its sustainability efforts with the WORLDSTAR 2025 Global Packaging Award and a Silver Award at the 2024 Anthem Awards, highlighting its innovative eco-friendly packaging and upcycling initiatives.
 - KYOCERA AVX has joined STMicroelectronics' Partner Program, expanding their collaboration on antenna solutions to enhance connectivity performance and accelerate time to market for ST customers.
 - Kyocera has begun full-scale development of an AI-powered 5G virtualised base station using NVIDIA's GH200 Grace Hopper Superchip, aiming to enhance performance, reduce power consumption, and expand 5G connectivity.
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Lattice

- Lattice Semiconductor's Nexus™ 2 FPGA platform won the 2025 SEAL Sustainable Product Award for its energy efficiency, high performance, and compact design.

Murata

- Murata has launched “CELLNETTA,” the world’s first metal cell fractionation filter, enabling rapid and precise target cell selection for regenerative medicine and biotechnology applications.
 - Murata Electronics (India) has leased a factory in Tamil Nadu to handle multilayer ceramic capacitor packaging and shipping, aiming for full-scale operations by FY2026.
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Nexperia

- Nexperia has expanded its e-mode GaN FET portfolio with 12 new devices, targeting consumer, industrial, computing, and telecom markets. The new offerings include 40V, 100V, 150V, 650V, and 700V devices, enhancing efficiency and compactness in applications like battery management, motor control, and power conversion.
 - Workers at Nexperia Philippines in Cabuyao, Laguna ended their 74-hour strike after securing a wage hike commitment, reinstatement of two union officers, and a no-retaliation guarantee.
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NVIDIA

- Nvidia CEO Jensen Huang will showcase new AI and quantum computing chips at the developer conference, emphasizing the Blackwell GPU line despite competition from China’s DeepSeek.
 - TSMC has proposed a joint venture to operate Intel’s foundry division, pitching stakes to Nvidia, AMD, Broadcom, and Qualcomm, though talks remain in early stages.
 - NVIDIA, Alphabet, and Google have announced new AI initiatives spanning robotics, drug discovery, and energy optimization, leveraging NVIDIA’s latest GPUs and AI platforms to accelerate innovation.
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NXP

- Green Hills Software and NXP have partnered to develop a hardware and software solution for the new S32K5 MCU family, enhancing safety, efficiency, and debugging for next-gen automotive applications.
- NXP has unveiled the S32K5 MCU at Embedded World 2025, featuring MRAM for faster OTA updates and deterministic networking for zonal SDV architectures.
- NXP Semiconductors secures a €1B EIB loan to boost R&D in Austria, France, Germany, the Netherlands, and Romania, strengthening Europe’s semiconductor ecosystem.

Onsemi

- Onsemi acquires Qorvo's SiC JFET technology for \$115M, enhancing its EliteSiC power portfolio and expanding its market by \$1.3B by 2030.
- Onsemi proposes to acquire Allegro MicroSystems for \$35.10 per share in cash, valuing the deal at \$6.9B and offering a 57% premium.
- Onsemi has launched its first-generation 1200V SiC MOSFET-based SPM 31 intelligent power modules (IPMs), delivering high energy efficiency and power density for three-phase inverter motor drives in applications like AI data centers, HVAC systems, and industrial automation.

Panasonic

- Panasonic's Fujisawa Sustainable Smart Town is a pioneering model of eco-conscious urban living, integrating smart technologies, renewable energy, and community-driven initiatives to achieve sustainability, resilience, and enhanced well-being for its residents.
- Panasonic has formed its first capital and business alliance with tado°, investing €30 million to integrate its Aquarea heat pump technology with tado°'s smart home energy management solutions, aiming to optimize heating efficiency, reduce energy consumption by up to 30%, and drive sustainable innovation in residential heating across Europe.
- Panasonic Connect has unveiled the NPM-GW Modular Placement Machine ahead of IPC APEX Expo 2025, showcasing a cutting-edge solution that enhances electronics manufacturing with high-speed precision, intelligent automation, and seamless integration into autonomous factory operations.

Rapidus

- Japan is strengthening its financial support for Rapidus to drive semiconductor production; however, sluggish private investment and industry skepticism present significant challenges, raising concerns over the government's substantial reliance on public funding.
- Japan's Rapidus is reportedly set to install 10 extreme ultraviolet (EUV) lithography machines across its semiconductor manufacturing facilities, IIM-1 and IIM-2, as part of its government-backed efforts to establish an advanced foundry and commence 2nm mass production by 2027.
- Broadcom has reportedly selected Rapidus as a supplier for 2nm chips, with sample deliveries expected by June 2025, positioning Rapidus to expand its market presence amid increasing competition in the semiconductor industry.

Renesas

- Future Electronics has launched the Renesas Wireless Connectivity Solutions hub, providing engineers with a dedicated resource for accessing Renesas' latest wireless technologies, development tools, and expert support to streamline product design and accelerate time-to-market.
 - Renesas has introduced the RZ/V2N MPU with an integrated AI accelerator, offering dual-camera processing and efficient edge AI computing in a compact, fanless design.
 - Renesas has launched the R-BMS F, a fixed-firmware battery management system designed for drones, robotics, and electric vehicles, offering pre-validated firmware and an easy-to-use GUI for simplified battery management.
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Samsung

- Samsung Electronics' leadership apologized for the company's stock decline and pledged to regain competitiveness through AI chip advancements and a major M&A deal in 2025.
 - Samsung will begin rolling out One UI 7 on April 7, introducing AI-driven features, enhanced personalization, and a streamlined design for Galaxy devices.
 - Samsung has launched the 9100 PRO PCIe 5.0 SSD in Singapore, boasting up to 14,800 MB/s read and 13,400 MB/s write speeds. Available in 1TB, 2TB, 4TB, and 8TB capacities, it offers improved power efficiency and enhanced heat management.
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Siemens

- Siemens plans to cut over 6,000 jobs worldwide, mainly in its factory automation unit, due to weak demand in China and Germany. About 5,600 cuts will happen by 2027, with half in Germany. The EV charging division will also reduce 450 jobs, shifting focus to fast-charging infrastructure.
 - Siemens' Cre8Ventures partners with Minima blockchain to enhance security and data authenticity in its digital twin marketplace and IoT applications.
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STMicroelectronics

- STMicroelectronics may cut up to 3,000 jobs in France and Italy as part of a \$300 million restructuring plan, focusing on advanced production facilities.
- TotalEnergies will supply 1.5 TWh of renewable power to STMicroelectronics in France over 15 years, supporting ST's goal of 100% renewable energy by 2027.
- Europe's semiconductor ambitions face setbacks as STMicroelectronics and GlobalFoundries shelve their €5.7 billion wafer fab project in France, shifting focus to China amid geopolitical and economic challenges.

Toshiba

- Synology and Toshiba have signed an MOU to strengthen their strategic partnership, reinforcing long-term collaboration in enterprise storage solutions.
 - Toshiba's new TB9103FTG gate driver IC enables compact, efficient control of automotive brushed DC motors.
 - Toshiba's SCiB™ battery enhances the safety and reliability of Thailand's electric motorcycle taxis, supporting carbon neutrality goals.
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Texas Instruments

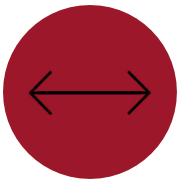
- Texas Instruments unveils power-management chips, including the TPS1685 hot-swap eFuse and GaN power stages, enhancing data center efficiency and power density.
 - Texas Instruments introduces the world's smallest MCU, the MSPM0C1104, optimizing space for compact applications like medical wearables and personal electronics.
 - Samsung, Texas Instruments, and Amkor finalize CHIPS Act funding agreements, securing \$4.75B, \$1.61B, and \$407M respectively to support semiconductor investments across Texas, Utah, and Arizona.
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TSMC

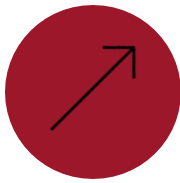
- Taiwan's President William Lai praises TSMC's \$100B investment in Arizona as a key step in building a "non-red" supply chain, strengthening U.S.-Taiwan ties and boosting advanced manufacturing jobs.
 - TSMC's \$100 billion U.S. investment showcases Taiwan's resilient semiconductor ecosystem, strengthening U.S.-Taiwan ties while adapting to geopolitical shifts.
 - Nvidia, TSMC, and Foxconn accelerate silicon photonic switch development, enhancing AI factory scalability, energy efficiency, and networking capabilities.
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Vishay

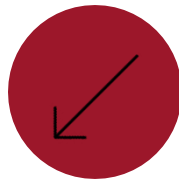
- Vishay launches AOCK series customizable control knobs for industrial use, enhancing usability across sectors like medical, transportation, and power tools.
- Vishay upgrades VSOP383xx series preamplifier circuits with Cyllene 2 IC, enhancing IR remote control performance with wider voltage range and improved noise immunity.
- Vishay unveils high-voltage MLCCs with extended capacitance, supporting commercial applications with up to 3000 VDC ratings and multiple dielectric options.



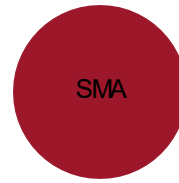
Stable



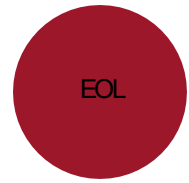
Increasing



Decreasing



Selective Market Adjustment



End of life

Analog		Pricing	Lead time	Lead time (weeks)
Standard	Amplifiers & Comparators	→	→	18+
	Analog Interface	→	→	18+
	Power Management	→	→	18+
	Converters	→	→	18+
Standard Analog total		→	→	18+
Advanced		→	→	18+
Mos Micrologic				
MPU		→	→	18+
MCU	8 bit & lower	→	→	12 - 18
	16 bit	→	→	18+
	32 bit & lower	→	→	12 - 18
MCU total		→	→	18+
Automotive MCU		→	→	28+
DSP		→	→	28+
Programmable logic		→	→	18+
Standard logic				
Timing products		→	→	28+
Interface		→	→	28+
Connectivity		→	→	28+
Standard logic		→	→	18+

Power			
FET	↓	→	18+
IGBT	→	→	18+
Rectifier	→	→	12 - 18
Other power	→	→	12 - 18
Memory	Pricing	Lead time	Lead time (weeks)
LE [Nor	→	→	18
	→	→	12 - 18
eMMC	→	→	12 - 18
EEprom	↓	→	4 - 10
Dram	→	→	12 - 18
Sram	→	→	4 - 10
Solid state drives	→	→	18+
Sensors			
	→	→	18+
OPTO			
LEDS (Low power)	→	→	4 - 10
LEDS (Mild power)	→	→	4 - 10
LEDS (High power)	→	→	12 - 18
Couplers	→	→	18
Fibre - Optic	→	→	18
Infrared	→	→	18
Other opto	→	→	18
Discrete			
Small signal	↓	→	12 - 18
RF	→	→	12 - 18

Analog

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Analog Devices	Sensors	10 - 26	↔	↔	
ams	Sensors	10- 26	↔	SMA	
Bosch sensortec	Sensors	8 - 14	↔	↔	
Diodes	Multi- Source Analog/Power	12 - 20	↔	↔	
	Switching Regulators	12 - 20	↔	↔	
FTDI Chip	Interface	12 - 16	↔	↔	
Infineon	Sensors	6 - 28	↔	↔	
	Switching Regulators	16 - 26	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22 - 26	↔	↔	
Maxlinear	Interface	22 - 28	↗	↔	
Melexis	Sensors	14 - 62	↔	SMA	
Microchip	Signal Chain (Amplifiers and Data Converters)	6 - 12	↔	↔	
	Timing	10 - 14	↔	↔	
	Switching Regulators	10 - 22	↔	↔	
Monolithic power systems	Switching Regulators	14 - 26	↔	↔	
NXP	Sensors	18 - 54	↔	↔	
	Interface	18 - 22	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	18 - 22	↔	↔	
Onsemi	Sensors	20 - 54	↔	SMA	
	Signal Chain (Amplifiers and Data Converters)	12 - 22	↔	↔	
	Timing	24 - 34	↗	↔	
	Multi- Source Analog/Power	12 - 22	↔	↔	
	Switching Regulators	12 - 22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Panasonic	Sensors	18 - 28	↗	↔	
Pericom Saronix-eCera	Timing	18 - 28	↗	↔	
Power Integrations	Switching Regulators	18 - 20	↔	↔	
Renesas	Signal Chain (Amplifiers and Data Converters)	14 - 22	↔	↔	
	Timing	16 - 20	↔	↔	
	Interface	16 - 22	↔	↔	
	Switching Regulators	16 - 26	↙	↔	
ROHM	Sensors	26 - 54	↔	↗	
	Switching Regulators	14 - 28	↔	↔	
ST Microelectronics	Sensors	22 - 36	↔	↔	
	Signal Chain (Amplifiers and Data Converters)	12 - 18	↔	↔	
	Multi- Source Analog/Power	12 - 20	↔	↔	
	Switching Regulators	12 - 22	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22 - 32	↔	↔	
TE Sensor Solutions	Sensors	18 - 54	↔	SME	
Texas Instruments	Regulators	18 - 22	↔	↔	
	Sensors	18 - 22	↔	↔	
	Interface	18 - 22	↔	↔	
Vishay	Sensors	26 - 54	↗	↔	

Batteries

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Alium Batteries	Lithium Ion	22 - 24	↔	↔	
Energizer	Alkaline	12 - 14	↔	↔	
	Lithium Metal	16 - 18	↔	↔	
	Silver Oxide	10 - 12	↔	↔	
GP Batteries	Alkaline	16 - 18	↔	↗	
	Lithium Metal	20 - 22	↔	↗	
	Lithium Ion	18 - 20	↔	↗	
	Nickle Metal Hydride	12 - 14	↔	↔	
	Lead Acid	10 - 12	↔	↔	
Panasonic	Carbon Zinc	10 - 12	↔	↔	
	Alkaline	12 - 14	↔	↔	
	Lithium Metal	16 - 18	↔	↔	
	Nickle Metal Hydride	10 - 12	↔	↔	
Rayovac	Carbon Zinc	10 - 12	↔	↔	
	Alkaline	10 - 12	↔	↔	
	Lithium Metal	12 - 14	↔	↔	
	Nickle Metal Hydride	10 - 12	↔	↗	
Renata Batteries	Carbon Zinc	10 - 12	↔	↔	
	Lithium Metal	16 - 18	↔	↔	
	Lithium Ion	22 - 24	↔	↔	
	Nickle Metal Hydride	12 - 14	↔	↗	
Tadiran Batteries	Silver Oxide	10 - 12	↔	↔	
	Carbon Zinc	10 - 12	↔	↔	
	Lithium Metal	14 - 16	↔	↔	
VARTA	Alkaline	12 - 14	↔	↔	
	Lithium Metal	20 - 26	↔	↔	
	Lithium Ion	34 - 40	↔	↔	
	Nickle Metal Hydride	12 - 14	↔	↗	

Connectivity

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Abracon	Antennas	10 - 14	↔	↔	
AMS	RFID	22	↗	↔	
Cel	802.15.4/Zigbee Modules	28 - 34	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers & Modulators, VCOs, SSBipolar Transistors, Wideband Transistors	32	↔	↔	
Infineon & Cypress	Bluetooth Modules Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SSBipolar Transistors, Wideband Transistors	18 - 26	↔	↔	Cypress is now Infineon
		14 - 18	↔	↔	
Fibocom	Cellular Modules	18 - 22	↔	↔	
Kyocera AVX	Antennas	10 - 12	↔	↔	
Laird connectivity	Wi-Fi Modules	18 - 38	↔	↔	
	Antennas	14 - 18	↗	↔	
	LoRa	32 - 54	↗	↔	
Linx Technologies	Cellular Modules	8 - 12	↔	↔	
	Antennas	12 - 14	↗	↔	
	Transceivers/Receivers	12 - 14	↗	↔	
Melexis	Transcivers/Recivers	18	↔	↔	
	RFID	16 - 18	↔	↔	
Microchip	Wi-Fi Modules	14 - 22	↔	↔	
	Bluetooth	14 - 22	↔	↔	
	Antennas	14 - 22	↔	↔	
	LoRa	18	↔	↔	
MultiTech	Cellular Modules	18 - 22	↔	↔	
	Antennasw	22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Murata	Wi-Fi Modules	28 - 52	↔	↔	
	Bluetooth Modules	28 - 52	↔	↔	
	Small Signal, Schottky, Diodes, PIN Diodes, Bipolar, Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14 - 22	↔	↔	
	LoRa	32 - 42	↔	↔	
Nearson	Antennas	10 - 12	↔	↔	
NXP	Multi-Protocol /Chip Solutions	28 - 38	↔	↗	
	Transceivers/Receivers	26	↔	↔	
	RFID 16 Parts on allocation	16	↔	↔	Parts on allocation
	High Power IC's	14 - 18	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SSBipolar Transistors, Wideband Transistors	14 - 18	↔	↔	
Onsemi	Bluetooth Modules	18 - 32	↔	↔	
Panasonic	Bluetooth Modules	18 - 28	↔	↔	
	RFID	16 - 18	↔	↔	
Pulse Electronics	Antennas	10 - 12	↔	↔	
Semtech	Transceivers/Receivers	12 - 14	↗	↔	
	LoRa	10 - 18	↔	↔	
Sierra Wireless	Multi-Protocol /Chip Solutions	42 - 48	↔	↔	Intel based radios are at 52 weeks
	Cellular Modules	14 - 18	↔	↔	
Silex Technology	Wi-Fi Modules	22 - 42	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ST Microelectronics	Bluetooth Modules	12 - 14	↔	↔	Capacity constraints on Spirit Radio RFID 22 ST25R39xx on allocation
	Transceivers/Receivers	14	↔	↔	
	Capacity constraints on Spirit Radio	22	↔	↔	
	RFID 22 ST25R39xx on allocation	14	↔	↔	
	GPS	22 - 32	↔	↔	
	High Power IC's	12 - 14	↔	↔	
	LoRa				
Synapse Wireless	802.15.4/Zigbee Modules	20 - 22	↔	↔	
Taoglas	Antennas	22 - 24	↗	↔	
TDK	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SSBipolar Transistors, Wideband Transistors	14 - 22	↔	↔	
TE Connectivity	Cellular Modules	8 - 12	↔	↔	
	Antennas	10 - 12	↗	↔	
	Transceivers/Receivers	10 - 14	↔	↔	
Thales	Cellular Modules	14 - 22	↔	↔	
U-Blox	Bluetooth Modules	14 - 28	↔	↔	Parts are on allocation, lead time is 26+
	Cellular Modules	14 - 28	↔	↔	
	GPS	14 - 28	↔	↔	Parts are on allocation and increasing in cost
	WiFi Modules	14 - 28	↔	↔	

Discrete

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Diodes Inc.	Low Voltage MOSFETS	12 - 26	↗	SMA	
	TVSDiodes	12 - 14	↘	↔	
	Bridge Rectifiers	10 - 18	↔	SMA	
	Schottky Diodes	10 - 14	↔	↔	
	Rectifiers	10 - 16	↔	SMA	
	Switching Diodes	10 - 14	↔	↔	
	Small Signal MOSFETS	10 - 14	↔	↔	
	Zener Diodes	10 - 14	↔	↔	
	Bipolar Transistors	10 - 14	↔	↔	
	Digital Transistors	10 - 14	↔	↔	
	General Purpose Transistors	10 - 14	↔	↔	
	Logic	10 - 12	↔	↔	
EATON	ESD	12 - 14	↔	↔	
	Fuses	10 - 14	↔	↔	
	Clips and Holders	12 - 16	↔	↔	
Everlight	Optocoupler Components	16 - 20	↔	↔	
Fairchild	Rectifiers	18 - 52	↘	↔	
	Optocoupler Components	12 - 20	↔	↔	
Infineon	Low Voltage MOSFETS	12 - 24	↗	SMA	
	High Voltage MOSFETS	10 - 22	↗	SMA	
	IGBTs	14 - 44	↗	SMA	
	Wide Bandgap Mosfets	10 - 42	↔	↔	
	Digital Transistors	8 - 32	↔	↔	
	General Purpose Transistors	12 - 32	↔	↔	
	Mil-Aero Transistors	20 - 28	↔	↔	
Texas Instruments	Logic	18 - 22	↔	↔	
Isocom Components	Optocoupler Components	4 - 6	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
IXYS	High Voltage MOSFETS	52 - 56	↔	↔	
	IGBTs	52 - 56	↔	↔	
Keystone	Clips and Holders	12 - 18	↔	SMA	
Kyocera	Varistors	16 - 20	↔	↔	
Lite-On	Optocoupler Components	14 - 16	↔	↔	
Littelfuse	ESD	12 - 14	↔	↔	
	Diode Arrays	12 - 14	↔	↔	
	Varistors	16 - 28	↔	↔	
	Wide Bandgap Mosfets	32 - 54	↔	↔	
	Fuses	10 - 14	↔	↔	
	PTC Fuses	10 - 14	↔	↔	
	Clips and Holders	12 - 16	↔	↔	
	Thyristors/Triacs	18 - 22	↔	↔	
	TVS Diodes	8 - 14	↙	↔	
	Sensors	18 - 32	↔	SMA	
Micro Commercial Components	Low Voltage MOSFETS	12 - 26	↗	↔	
	High Voltage MOSFETS	14 - 32	↗	↔	
	ESD	12 - 14	↔	↔	
	TVS Diodes	10 - 12	↔	↔	
	Schottky Diodes	10 - 14	↔	↔	
	Switching Diodes	10 - 14	↔	↔	
	Small Signal Mosfets	12 - 16	↔	↔	
	Zener Diodes	12 - 16	↔	↔	
	Bipolar Transistors	10 - 16	↔	↔	
	General Purpose Transistors	10 - 16	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Microchip	High Voltage Mosfets	6 - 28	↗	↔	
	Wide BandGap Mosfets	10 - 24	↔	↔	
Microsemi	High Voltage MOSFETS	44 - 54	↔	↔	
	IGBTs	44 - 54	↔	↔	
	Mil-Aero Diodes	28 - 54	↔	↔	
	Mil-Aero Transistors	34 - 62	↔	↔	
	Low Voltage MOSFETS	8 - 16	↔	SMA	
Nexperia	ESD	8 - 12	↔	↔	
	Schottky Diodes	8 - 10	↔	↔	
	Switching Diodes	8 - 10	↘	↔	
	Small Signal MOSFETS	8 - 10	↔	↔	
	Zener Diodes	8 - 10	↔	↔	
	Bipolar Transistors	8 - 10	↔	↔	
	Digital Transistors	8 - 10	↔	↔	
	General Purpose Transistors	8 - 10	↔	↔	
	Logic	8 - 10	↔	↔	
	ON Semiconductor	Low Voltage MOSFETS	12 - 26	↗	SMA
High Voltage MOSFETS		14 - 24	↗	SMA	
ESD		10 - 16	↗	↔	
Wide Bandgap Mosfets		10 - 40	↔	↔	
Schottky Diodes		12 - 32	↔	↔	
Rectifiers		18 - 32	↔	SMA	
Switching Diodes		12 - 32	↔	↔	
Small Signal MOSFETS		12 - 32	↔	↔	
Zener Diodes		12 - 32	↔	↔	
Bipolar Transistors		12 - 32	↔	↔	
Digital Transistors		12 - 32	↔	↔	
General Purpose Transistors		12 - 32	↘	↔	
Logic		10 - 16	↘	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ProTek Devices	Diode Arrays	10 - 22	↔	↔	
Renesas	Optocoupler Components	20 - 22	↔	SMA	
ROHM	High Voltage MOSFETS	14 - 26	↗	↔	
	Wide Bandgap Mosfets	22 - 30	↔	↔	
	Schottky Diodes	14 - 22	↔	↔	
	Switching Diodes	14 - 22	↔	↔	
	Digital Transistors	14 - 18	↔	↔	
	General Purpose Transistors	14 - 18	↔	↔	
Schurter	Fuses	20 - 26	↔	↗	
	Clips and Holders	22 - 32	↔	↗	
Semtech	Diode Arrays	10 - 14	↔	↔	
STMicroelectronics	Low Voltage MOSFETS	16 - 28	↗	SMA	
	High Voltage MOSFETS	16 - 28	↔	SMA	
	IGBTs	16 - 22	↔	SMA	
	ESD	18 - 20	↔	↔	
	Wide Bandgap Mosfets	35 - 48	↔	SMA	
	Thyristors/Triacs	18 - 20	↔	↔	
	TVSDiodes	18 - 20	↔	↔	
	Rectifiers	16 - 18	↔	SMA	
	Bipolar Transistors	14 - 26	↔	↔	
TDKEPCOS	Varistors	16 - 22	↔	↔	
TE Connectivity	PTC Fuses	10 - 14	↔	↔	
Vishay	Low Voltage MOSFETS	8 - 32	↗	SMA	
	High Voltage MOSFETS	14 - 32	↗	SMA	
	TVSDiodes	10 - 14	↔	↔	
	Bridge Rectifiers	10 - 12	↔	SMA	
	Rectifiers	10 - 12	↔	SMA	
	Zener Diodes	12 - 16	↔	↔	
	Optocoupler Components	6 - 14	↔	↔	

Electromechanical

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Abracon	Timing	14 - 54+	↙	SMA	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
ADDA	Fans	22 - 26	↔	↔	
Alps Electric	Switches	26 - 34	↔	↔	
American Zettler	Relays	18 - 32	↔	↔	
Bivar	Hardware	12 - 18	↔	↔	
Boyd	Fans	14 - 16	↔	↔	
	Heatsinks	18 - 26	↔	↔	
C&K	Switches	14 - 32	↔	↔	
Churod Electronics	Relays	10 - 32	↔	↔	
Citizen Finedevice	Timing	14 - 54	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
COSEL	Power Supplies (AC/DC)	14 - 38	↙	↔	
	Power Supplies (DC/DC)	14 - 38	↔	↔	
CTS	Switches	10 - 12	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
	Timing	12 - 32	↔	↔	
CUI Inc	Power Supplies (AC/DC)	26 - 54+	↔	↔	
	Power Supplies (DC/DC)	14 - 38	↙	↔	
	Heatsinks	12 - 14	↔	↔	
Delta	Fans	26 - 34	↔	↔	
Diodes Inc	Timing	10 - 14	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
E-Switch	Switches	14 - 16	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ECS Inc.	Timing	14 - 42	↙	SMA	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
EPSON Electronics America	Timing	14 - 28	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
Essentra Components	Hardware	14 - 16	↔	↔	
Fox	Timing	12 - 42+	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
Grayhill	Switches	14 - 26	↔	↔	
Heyco	Hardware	12 - 14	↔	↔	
Hongfa	Relays	18 - 32	↔	SME	
Infineon	Relays	42 - 54	↔	↗	
IXYS	Relays	12 - 32	↔	↔	
Keystone	Hardware	14 - 16	↔	↔	
Kyocera International	Timing	18 - 30	↙	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
MEAN WELL	Power Supplies (AC/DC)	16 - 20	↔	↔	
Microchip	Timing	14 - 28	↔	↗	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
Murata	Timing	10 - 12	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Murata Power Solutions	Power Supplies (AC/DC)	10-12	↔	↔	
NKK Switches	Switches	12 - 20	↔	↔	
NMB	Fans	28 - 42	↔	↔	
Ohmite	Fans	12 - 14			
Orion Fans	Fans	18 - 20	↔	↔	
Panasonic	Relays	16 - 32	↔	↔	
	Switches	12 - 14	↔	↔	
Qualtek	Fans	22 - 26	↔	↔	
Raltron	Timing	12 - 42	↔	↔	Tuning Forks- 32.7668KHZ and 40-52+ weeks, TCXOs are on allocation due to AKM fire
RECOM	Power Supplies (AC/DC)	18 - 42	↔	↔	
	Power Supplies (DC/DC)	16 - 38	↔	↔	
Rosenberg	Fans	20 - 22	↔	↔	
Schneider Electric	Relays	18 - 20	↔	↔	
Song Chuan	Relays	26 - 38	↔	↔	
SUNON	Fans	32 - 44	↔	↔	
TE Connectivity Sensors	Relays				
	All stable except the IM ready Series-	14 - 16	↔	↔	All stable except the IM ready Series allocation 52+ weeks
	allocation 52+ weeks	12 - 14	↔	↔	
Switches					
Vicor	Power Supplies (AC/DC) 28-54	28 - 54	↔	↔	
	Power Supplies (DC/DC)	28 - 54	↔	↔	
Wakefield Thermal	Heatsinks	12 - 14	↔	↔	
Wall Industries	Power Supplies (AC/DC)	10 - 12	↔	↔	
	Power Supplies (DC/DC)	10 - 12	↔	↔	
ZF Electronics	Switches	20 - 22	↔	↔	

High - End

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
AZ Displays	LCDS	14 - 16	↔	↔	
Compulab	SOM	18	↔	↔	
Cypress	8 bit MCU	12 - 18	↔	↔	
	32 bit MCU	12 - 54	↔	↔	
	USB	44 - 54	↔	↔	
	Automotive	34 - 48	↔	↔	
Formerica	Fibre Optic Transceivers	14 - 18	↔	↔	
Infineon	Automotive	Allocation	↔	↔	
iWave Systems	SOM	18	↔	↔	
Lattice Semiconductor	FPGA	18 - 26	↘	↘	
Microchip	8 Bit MCU	6 - 14	↔	↔	
	32 bit MCU	6 - 20	↔	↔	
	PHY/Ethernet	8 - 14	↔	↔	
	USB	8 - 12	↔	↔	
	32 bit MPU	6 - 22	↔	↔	
Microsemi	FPGA	10 - 34	↔	↔	
NXP	8 Bit MCU	15 - 42	↔	↔	
	32 bit MCU	15 - 42	↔	↔	
	Automotive	20 - 54	↔	↔	
	32 bit MPU	20 - 42	↔	↔	
	Network Processors	20 - 44	↔	↔	
Renesas RA	32 bit MCU	20	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Renesas	8 Bit MCU	14 - 20	↗	↔	
	32 bit MCU	14 - 20	↗	↔	
	Automotive	48	↔	↔	
	32 bit MPU	14	↔	↔	
Sharp	LCDs	22 - 24	↔	↔	
STMicroelectronics	8 bit MCU	12 - 26	↗	↔	
	Automotive	42 - 54	↔	↔	
	32 bit MPU	18 - 22	↔	↔	
	STEM32F0 - 32 bit MCU	12 - 14	↔	↔	
	STEM32F1 - 32 bit MCU	12 - 14	↔	↔	
	STEM32L - 32 bit MCU	12 - 14	↗	↘	
	Balance 32 bit MCU	12 - 14	↗	↘	
STM32F2/F4/F7/H7	12 - 18	↗	↘		
Texas Instruments	MCUs & Processors	30 - 32	↔	↔	
Xilinx	FPGA	18 - 22	↔	↔	
Zilog	8 bit MCU	26 - 42	↔	↔	

Interconnect

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Adam Tech	I/O Connectors	18 - 20	↔	↔	
	PCB Connectors	18 - 20	↔	↔	
Altech Corp.	Terminal Blocks & Crimps	14	↔	↗	
Amphenol Communications Solutions	D-Sub Connectors	10 - 12	↔	↔	
	Data & Telecom	10 - 12	↔	↔	
	PCB Connectors	10 - 12	↔	↔	
	FFC/FPC	10 - 12	↔	↔	
Amphenol Sine System	Circular Connectors	10 - 22	↔	↗	
ASSMAN WSW Components	Data & Telecom	22	↔	↔	
	PCB Connectors	22	↔	↔	
	IC Sockets	22	↔	↔	
Bulgin	Circular Connectors	18 - 20	↔	↗	
EDAC	PCB Connectors	16 - 24	↔	↔	
Global Connector Technology	PCB Connectors	10 - 12	↔	↗	
	FFC/FPC	10 - 12	↔	↗	
HALO Electronics	Data & Telecom	14 - 20	↔	↔	
HARTING	PCB Connectors	12 - 14	↔	↔	
Hirose Electric	PCB Connectors	10 - 18	↔	↔	
	RF Connectors	10 - 18	↔	↔	
	FFC/FPC	10 - 18	↔	↔	
JST	PCB Connectors	18	↔	↔	
Mil-Max	PCB Connectors	6 - 8	↔	↗	
	IC Sockets	6 - 8	↔	↔	
Oupiin	PCB Connectors	16 - 22	↔	↔	
Sullins	PCB Connectors	8 - 10	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
TE Connectivity	Automotive Connectors	14 - 18	↔	↗	
	Circular Connectors	14 - 18	↔	↗	
	Relays	14 - 18	↔	↗	
	Data & Telecom	14 - 18	↔	↔	
	PCB Connectors	14 - 18	↔	↔	
	RF Connectors	14 - 18	↔	↔	
	IC Sockets	14 - 18	↔	↔	
	Terminal Blocks & Crimps	14 - 18	↔	↔	
	Lighting Connectors	14 - 18	↔	↗	
WAGO	Terminal Blocks & Crimps	16	↔	↗	
	Lighting Connectors	16	↔	↔	
WECO	Terminal Blocks & Crimps	22 - 26	↗	↔	

Lighting solutions & opto

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Bridgelux	Chip On Board (CoB)	8 - 10	↔	↔	
Dialight	Indication LEDs	12 - 18	↔	↔	
	6V (LED Optics)	12 - 18	↔	↔	
Everlight	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
	Everlight Infrared Components/ LED	16 - 18	↔	↔	
	Indication LEDs	16 - 18	↔	↔	
	UV LEDs	10 - 12	↔	↔	
Excellence Optoelectronics Inc.	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
General Luminaire	Standard Light Engines (Level 2 Boards)	16 - 18	↔	↔	
Inolux	Indication LEDs	8 - 10	↔	↔	
Kingbright	LED Displays	12 - 14	↔	↔	
	Indication LEDs	10 - 12	↔	↔	
Lite-On	Infrared Components/ LED 16-18	16 - 18	↔	↔	
	Lite-On LED Displays	16 - 18	↔	↔	
	Indication LEDs	18 - 22	↔	↔	
Lumex	LED Displays 18	14	↔	↔	
	Indication LEDs	10 - 16	↔	↔	
Lumileds	Illumination High Power LEDs (White)	10 - 16	↔	↗	
		10 - 16	↔	↗	
	Horitcultural Mid Power LEDs (White & Colors)	10 - 12	↔	↗	
	Automotive LEDs (AEC-Q101 Certified)	10 - 12	↔	↔	
	Chip On Board (CoB)	16 - 18	↔	↗	
		10 - 12	↔	↔	
	Standard Light Engines (Level 2 Boards)	20 - 28	↔	↔	
	Infrared Components/ LED 28	28	↔	↔	
	UV LEDs	14 - 18	↔	↗	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Meanwell	LED Drivers	12 - 22	↔	↔	
Murata	Lighting Controls	28 - 32	↔	↔	
Nichia	Illumination High Power LEDs (White & Colors)	8 - 12	↔	↔	
		8 - 12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10 - 12	↔	↔	
	Chip On Board (CoB)	10 - 12	↔	↔	
		14 - 16	↔	↔	
ROHM	Infrared Components/ LED	8 - 10	↔	↔	
	Indication LEDs	12 - 14	↔	↔	
Samsung LED	Illumination High Power LEDs (White)	8 - 10	↔	↔	
		10 - 12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10 - 12	↔	↔	
	Chip On Board (CoB)	8 - 10	↔	↔	
		8 - 10	↔	↔	
	Standard Light Engines (Level 2 Boards)		↔	↔	
Seoul Semiconductor	Illumination High Power LEDs (White)	8 - 10	↔	↔	
		8 - 10	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	8 - 10	↔	SMA	
	Chip On Board (CoB)	10 - 12	↔	↔	
		12 - 14	↔	↔	
	Standard Light Engines (Level 2 Boards)		↔	↔	
Seoul Viosys	UV LEDs	12 - 18	↔	↔	
Stanley Electric	LED Displays 14	14	↔	↔	
	Indication LEDs	12 - 14	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
TE Connectivity	6A (Heat Sinks, LED Holders)	22 - 52	↔	↔	
TT Electronics-Optek Technology	Infrared Components/ LED	28 - 46	↔	↗	
VCC	Indication LEDs	12 - 14	↔	↔	
	Infrared Components/ LED	10 - 22	↔	↔	
Vishay	Indication LEDs	10 - 32	↔	↗	
	UV LEDs	16 - 18	↔	↔	

Memory

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
ADATA	Memory Modules	8 - 10	↔	↗	
	eMMC	8 - 10	↔	↗	
	Memory Cards	10 - 12	↔	↔	
	Solid State Drives (SSD)	10 - 12	↔	↔	
Alliance Memory	PC Commodity DRAM	4 - 22	↔	↔	
	Mobile RAM	10 - 18	↔	↔	
	Spram	10 - 32	↘	↔	
	NOR Flash	14 - 22	↔	↔	
	Nand Flash	10 - 26	↘	↔	
Cypress	eMMC	10 - 14	↔	↔	
	SPRAM	14 - 54	↘	↔	
	NOR Flash	14 - 28	↘	↔	
Everspin Technologies	FRAM & NVSPRAM	14 - 28	↘	↔	
	MRAM	14 - 30	↔	↔	
Greenliant	NOR Flash	10 - 18	↔	↔	
	eMMC	14 - 20	↗	↗	
	Memory Cards	10 - 18	↔	↔	
	Solid State Drives (SSD)	10 - 18	↔	↔	
Kingston	PC (Commodity) DRAM	4 - 6	↔	SMA	
	Memory Module	4 - 8	↔	↔	
	Memory Module eMMC	6 - 8	↔	↗	
	Memory Cards	4 - 12	↔	↗	
	Solid State Drives (SSD)	6 - 10	↔	↗	
Macronix	NOR Flash	10 - 14	↔	↔	Parts on allocation, MXIC is not quoting and not taking new orders for the time being
	NAND Flash	10 - 14	↔	SMA	
	eMMC	20 - 28	↔	↗	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Microchip	SPAM	6 - 14	↙	↔	
	NOR Flash	6 - 28	↙	↔	
	EEPROM	6 - 28	↔	↔	
	EPROM	14 - 28	↔	↗	
Onsemi	SPAM	22 - 42	↔	↔	
	EEPROM	14 - 22	↙	↔	
Renesas	SPRAM	14 - 16	↙	↔	
	NOR FLASH	14 - 16	↙	↔	
	DATAFLASH	14 - 16	↙	↔	
Samsung LED	PC (Commodity) DRAM	54 - 56	↔	↔	
	Memory Modules	54 - 56	↔	↔	
	eMMC	54 - 56	↔	↔	
	Solid State Drivers (SSD)	54 - 56	↔	↔	
SkyHighMemory	SLC NAND Flash	8 - 12	↙	↔	
	eMMC	10 - 14	↔	↔	
STMicroelectronics	EEPROM	6 - 10	↔	↔	

Passives

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Apl Delevan	Inductors	16 - 18	↔	↔	
Cornell Dubilier Electronics	Electrolytic	24 - 48	↔	↔	
	Capacitor	28 - 42	↔	↔	
CTS	Resistor Networks	18 - 22	↔	↗	
Eaton	Capacitors - Supercapacitors	12 - 22	↘	↔	
	Inductors	22 - 32	↘	↔	
ELNA	Capacitors - Supercapacitors	32 - 42	↘	↔	
HALO Electronics	Inductors	16 - 18	↘	↔	
Murata	Filters	14 - 18	↔	↔	
	Inductor / Transformers	14 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	12 - 16	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	12 - 14	↔	↔	
	Leaded Capacitors - Ceramic	18 - 20	↔	↔	
	Specialty Capacitors	18	↔	↔	
	Surface Mount General Capacitors	16 - 18	↔	↔	
NIC Components	Electrolytic	24 - 32	↘	↔	
	Filters	16 - 22	↔	↔	
	Inductors	16 - 22	↔	↔	
	Fixed Resistors	14 - 20	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	20 - 22	↔	↔	
	Leaded Capacitors - Ceramic	14 - 16	↔	↔	
		28 - 30	↔	↔	
Nichicon	Electrolytic	20 - 32	↘	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
Panasonic	Electrolytic	20 - 32	↗	↔	
	Capacitors- Polymer Tantalum	12 - 14	↗	↔	
	Inductors / Transformers	20 - 24	↔	↔	
	Fixed Resistors	22 - 32	↔	↔	
	Resistor Networks	20 - 30	↔	↔	
Paktron Capacitors	Capacitors- Film	14 - 18	↔	↔	
Samsung Electro-Mechanics	Fixed Resistors				
	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	46 - 48	↔	↔	
	Surface Mount General Capacitors – Ceramic (Great than 1 uf)	46 - 48	↔	↔	
	Surface Mount General Capacitors-Ceramic *Automotive Upgrade	14 - 16	↔	↔	
Stackpole Electronics	Fixed Resistors	18 - 26	↔	↔	
Sumida	Inductors	22 - 26	↔	↔	
Taiyo Yuden	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	16 - 20	↔	↔	
	Surface Mount General Capacitors- Ceramic (Greater than 1 uf)	22 - 24	↔	↔	
	Surface Mount General Capacitors - Ceramic *Automotive Upgrade	22 - 24	↔	↔	
	Filters				
TDK	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	14 - 18	↗	↗	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	22 - 26	↔	↔	
	Surface Mount General Capacitors - Ceramic *Automotive Upgrade	26 - 38	↔	↔	
	Surface Mount General Capacitors - Ceramic *Automotive Upgrade	26 - 32	↔	↔	
TDKEPCOS	Capacitors- Film	26 - 35	↘	↔	
	Filters	14 - 18	↗	↔	
	Inductors / Transformers	18 - 22	↔	↔	

Manufactures	Products	Lead time (weeks)	Trend	Pricing	Comments
TT Electronics- BI Technologies	Trimmers & Pots	18 - 22	↔	↔	
TT Electronics- IRC	Fixed Resistors	22 - 42	↔	↔	
United Chemi-Con	Electrolytic	24 - 36	↗	↔	
Viking	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	18 - 20	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	16 - 18	↔	↔	
Vishay	Trimmers & Pots	12 - 22	↔	↔	
	Capacitors- Film	14 - 22	↔	↔	
	Capacitors- Supercapacitors	14 - 16	↔	↔	
	Capacitors- Tantalum Molded	18 - 20	↘	↔	
	Capacitors- Tantalum Conformals	14 - 16	↔	↔	
	Capacitors- Polymer Tantalum	14 - 16	↔	↔	
	Inductors / Transformers	14 - 16	↔	↔	
	Fixed Resistors	12 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	16 - 18	↔	↔	
	Leaded Capacitors - Ceramic	20 - 26	↔	↔	
	Specialty Capacitors	28 - 36	↔	↔	
WIMA	Capacitors- Film	14 - 18	↔	↔	
Würth Elektronik	Inductors / Transformers	20 - 22	↔	↔	
Yageo	Fixed Resistors				
	Resistor Networks	20 - 22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	22 - 26	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	16 - 18	↔	↔	
	Surface Mount General Capacitors - Ceramic*Automotive Upgrade	16 - 18	↔	↔	

Market Insights

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Senior Commercial Analyst

Jenny Ortila



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